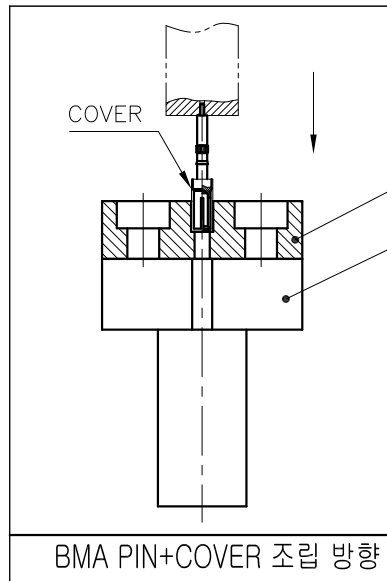
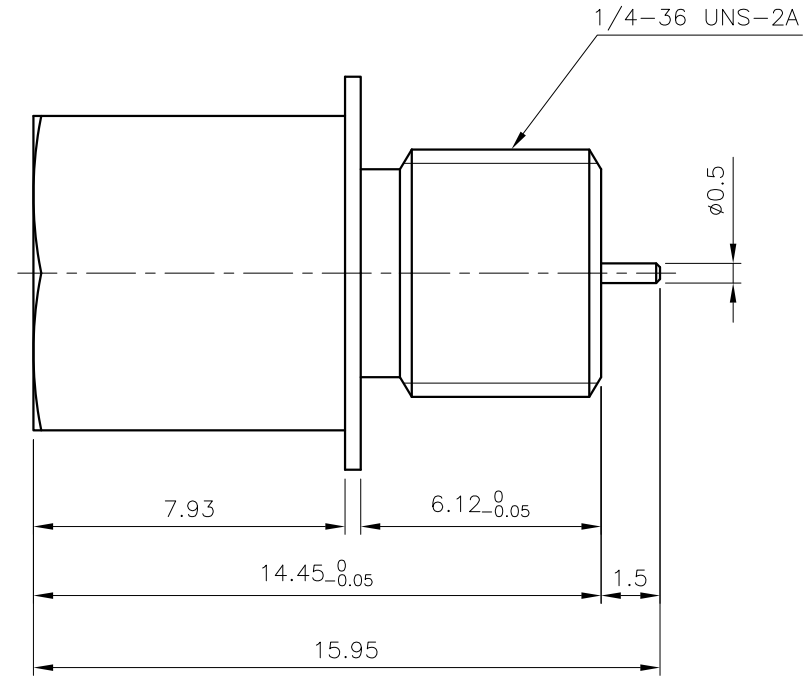
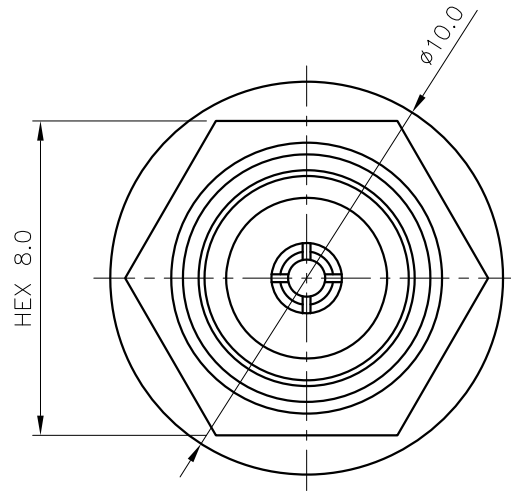
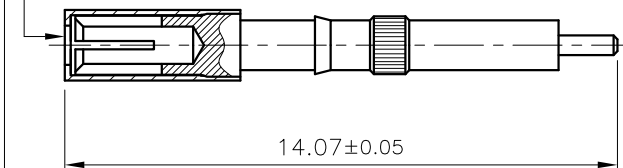


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	S.H.KIM		2023.05.11.



CEQ00429-N/1
CEQ00429-N/2

상대물 핀 사이즈 ø0.90~ø0.94



5	PLATE SPRING	1	BeCu C17300	Gold Plate	DPS00002-5/1
4	COVER		MBsBD C3604BD-F	Gold Plate	DIB00026-5/1
3	INSULATOR	1	TEFLON		DIN02185-N/2
2	CONTACT	1	BeCu C17300	Gold Plate (1.27μm)	DCT02848-5/2
1	BODY	1	SUS303	Passivate	DBD03340-5/2
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal ±0.2	DATE 2023. 05. 11.	
	Angle ±1°	APPROVED BY	
MATERIAL		CHECKED BY	
		DRAWN BY S.H.KIM	
FINISH		SCALE 5/1	UNIT mm



TITLE BMA50 SOLDER END JB(F/F)			
A4	DWG NO. CN02999-7/3		
REVISION	I R	SHEET	1 of 1